

## THERMAL INTERFACE APPARATUS, SYSTEMS, AND METHODS

### Abstract of the Disclosure

5      An apparatus and system, as well as fabrication methods therefor, may include a unitary layer of electrically non-conductive material having a first surface adjacent a heat sink, a second surface adjacent a heat source, and a plurality of openings that may be communicatively coupled between the first surface and the second surface, wherein the combined area of the plurality of openings comprises a selected percentage of the first surface.

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